CLAIMS

1. A sheet-form thermosetting resin composition for sealing an electronic component,

comprising silica in an amount of 70 to 93% by weight to a whole of the sheet-form thermosetting resin composition for sealing an electronic component;

meeting the flame retardancy regulation (UL94V-0);

having a three-point bending strength of 80 MPa or more at normal temperature after the resin composition is cured under heating at 150°C for 1 hour; ~~and~~

further comprising a thermoplastic resin; and

wherein the sheet-form thermosetting resin composition does not contain metal hydroxide.

2. The sheet-form thermosetting resin composition for sealing an electronic component according to claim 1, wherein the silica has an average particle size of 0.1 to 30 μm.

3. The sheet-form thermosetting resin composition for sealing an electronic component according to claim 1 or 2, having a viscosity of 5×10^3 Pa·s or less at 90°C before curing.

4. The sheet-form thermosetting resin composition for sealing an electronic component according to any one of claims 1 to 3, which is manufactured by kneading extrusion.

5. The sheet-form thermosetting resin composition for